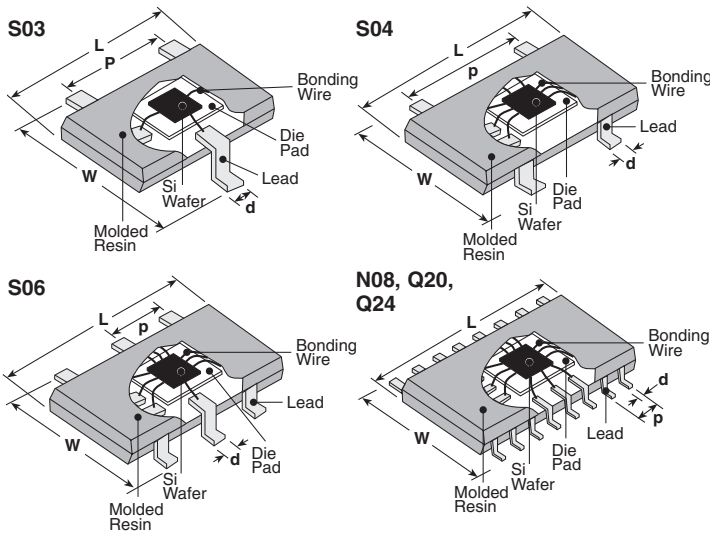


### features

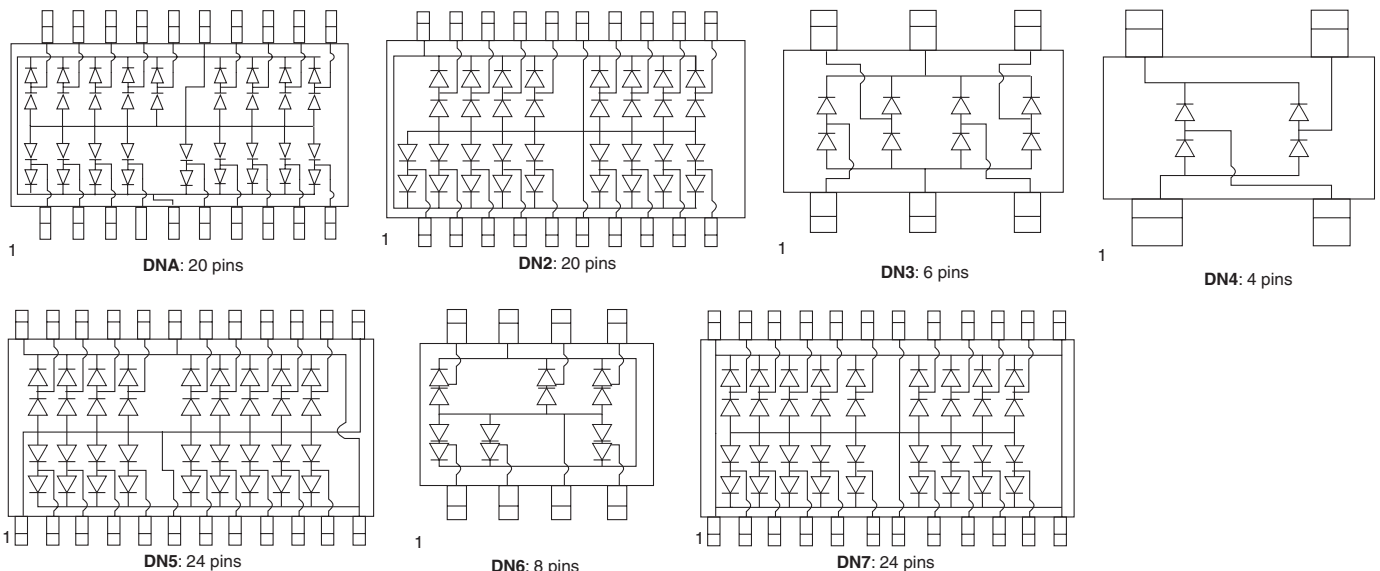
- Fast reverse recovery time
- Fast turn on time
- Low capacitance
- SMD packages
- 16 kV IEC61000-4-2 capable
- Products with lead-free terminations meet EU RoHS and China RoHS requirements

### dimensions and construction



Package Code	Total Power	Pins	Dimensions inches (mm)				
			L ±0.2	W ±0.2	p ±0.1	Pkg Ht ±0.2	d ±0.05
S03	225mw	3	.115 (2.92)	.091 (2.30)	.075 (1.91)	.037 (0.95)	.017 (0.43)
S04	225mw	4	.115 (2.92)	.091 (2.30)	.075 (1.91)	.037 (0.95)	.017 (0.43)
S06	225mw	6	.115 (2.92)	.110 (2.80)	.037 (0.95)	.037 (0.95)	.017 (0.43)
N08	400mw	8	.190 (4.83)	.236 (5.99)	.050 (1.27)	.063 (1.60)	.016 (0.41)
Q20	1000mw	20	.341 (8.66)	.236 (5.99)	.025 (0.635)	.063 (1.60)	.010 (0.25)
Q24	1000mw	24	.341 (8.66)	.236 (5.99)	.025 (0.635)	.063 (1.60)	.010 (0.25)

### circuit schematic



For further information on packaging, please refer to Appendix A.

Specifications given herein may be changed at any time without prior notice. Please confirm technical specifications before you order and/or use.

12/28/10

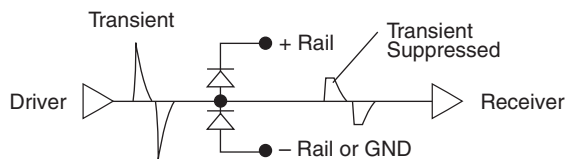
## ordering information

DNA	Q20	T	TEB
<b>Type</b>	<b>Package Symbol</b>	<b>Termination Material</b>	<b>Packaging</b>
DNA DN2 DN3 DN4 DN5 DN6 DN7	Package type symbol + number of pins S03: 3 pin SOT23 S04: 4 pin SOT23 S06: 6 pin SOT23 N08: 8 pin Narrow SOIC Q20: 20 pin QSOP Q24: 24 pin QSOP	T: Sn (Other termination styles available, contact factory for options)	TE: 7" embossed plastic (SOT23 only) TEB: 13" embossed plastic

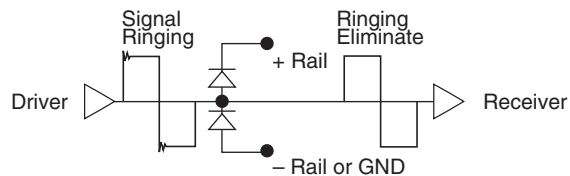
For further information on packaging, please refer to Appendix A.

## application schematic

### ESD Suppression



### Signal Conditioning



## applications and ratings

Part Designation	Forward Voltage $I_F=50\text{ma}$	Reverse Breakdown Voltage $I_R=1\text{ma}$	Leakage Current @7V	Capacitance @1Mhz	ESD Voltage Capability IEC 61000-4-2	Operating Temperature Range	Continuous Forward Current*
DN(X)	0.4 to 1.2V	7.2V	1 $\mu$ A	2pF	16kV	-55°C to +155°C	50mA

\* One diode conducting